

Title (en)
POLISHING SLURRY AND POLISHED SUBSTRATE

Title (de)
POLIERSUSPENSION UND POLIERTES SUBSTRAT

Title (fr)
PATE DE POLISSAGE ET SUBSTRAT POLI

Publication
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Application
EP 03758887 A 20031024

Priority
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Abstract (en)
[origin: WO2004037943A1] A polishing slurry comprising an abrasive comprising as a basic ingredient rare earth oxides containing cerium oxide, which polishing slurry further comprises an anionic surfactant and a nonionic surfactant and has a pH value of at least 11. The polishing slurry is especially suitable for polishing a glass substrate for magnetic disc, and other substrates used in electronic field.

IPC 1-7
C09K 3/14; **C09G 1/02**; **H01L 21/768**

IPC 8 full level
B24B 1/00 (2006.01); **B24D 3/02** (2006.01); **C09G 1/02** (2006.01); **C09K 3/14** (2006.01); **H01L 21/768** (2006.01)

CPC (source: EP US)
C09G 1/02 (2013.01 - EP US); **C09K 3/1463** (2013.01 - EP US)

Citation (search report)
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